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Heat Transfer Characteristics of Flow Between Two Parallel Plates

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by (Font size 12, Times New Roman and Centered)

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(Md. Ruhul Amin) (Font size 12, Bold, Times New Roman and Centered)

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> University Monogram (Three Blank Lines) Khulna University of Engineering & Technology Khulna 920300, Bangladesh (Font size 12, Times New Roman and Centered) April 2005 (Font size 12, Bold, Times New Roman and Centered)

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Contents

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			PAGE (Font size 12, Bold, Times New Roman and Centered)
Title Page			i i
Declaratio	n		ii
Certificate	of Research		iii
Acknowle	dgement		iv
Abstract	-8	(Font size 12, Times New	V
Contents		Roman and Left Indent)	vi
List of Tab	oles		vii
List of Fig	ures		viii
List of Illu	strations		Х
Nomenclature			xi
CHAPTER I	Introduction		1
(Font size 12, Bold,	1.1		1
Times New Roman	1.2		2
unu Centereu)	1.3		2
	1.4		3
CHAPTER II	Literature Review		5
	2.1		5
	2.2	(Font size 12, Times New	15
	2.3	Roman and Left Indent)	20
	2.4		22
CHAPTER III	Procedure / Methodology		26
	3.1	(Font size 12 Times New	26
	3.2	Roman and Left Indent)	29
	3.3	Roman and Left Indent)	30
	3.4		44
CHAPTER IV	Results and Discussi	on	52
	4.1	(Font size 12, Times New	52
	4.2	Roman and Left Indent)	54
	4.3	•	58
CHAPTER V	Conclusions and Recommendations		70
	(Font size 12, Times	New Roman and Left Indent)	
Reference	es		73
(Font size	e 12, Times New Roma	n and Left Indent)	
Appendic	es		76
(Font size	212, Times New Roma	n and Left Indent)	

LIST OF TABLES

(Font size 14, Bold, Times New Roman and Centered) (One Blank Lines)

Table No	le No Description	
2.1	Pentium Classic-Power dissipation	
	requirements for thermal design.	2
3.1	Variation of temperature recorder reading	1.5
	with thermometer reading.	15
3.4	Experimental data for heat sink type A.	20
3.5	Experimental data for heat sink type N.	21
3.6	Experimental data for heat sink type B.	23
3.7	Experimental data for heat sink type X.	25
3.8	Experimental data for heat sink type D.	27
3.9	Experimental data for heat sink (Pin fin).	28 28
3.10	Experimental data for thermal conductivity.	31
3.11	Experimental data for heat sink (Constructed).	31
4.1	Experimental result for heat sink type A.	32
4.2	Experimental result for heat sink type N	32
	Enperimental result for near shirt type 14.	32

LIST OF FIGURES

(Font size 14, Bold, Times New Roman and Centered) (One Blank Lines)

Figure No	Description	Page
2.1	Cooling fan	3
2.2	Liquid Cooling	4
2.3	Cooling of microprocessor with heat sink	4
2.4	Heat sink with flat fins	5
2.5	Heat sink with pin fins	5
2.6	Folded fins heat sink	5
2.7	Conduction & convection through a rectangular fin	6
3.1	Experimental Setup (Top View)	13
3.2	Front view of experimental setup	14
3.3	Circuit diagram of experimental setup	14
3.4	Calibration curve of temperature recorder	16
3.5	Heat sink (type A)	17
3.6	Front View (Type A)	17
3.7	Heat sink (Type N)	19
3.8	Front view (Type N)	19
3.9	Heat sink (Type B)	21

LIST OF ILLUSTRATIONS

(Font size 14, Bold, Times New Roman and Centered) (One Blank Lines)

Illustration No	Description	Page
2.1	Pentium Classic-Power dissipation requirements for thermal design.	33
2.5	Experimental setup	43
3.1	Flow Visualization of the Phenomena	44
3.9	Color Doppler view of heat sink type N	56
4.3	Color Doppler view of heat sink (Constructed)	66
4.5	Isotherms in the test section over heat sink type A.	69
4.4	Velocity vector plot over heat sink type B	70

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C_p Co-efficient of Pressure,
$$\frac{(P - P_a)}{2 p v_j^2}$$

d	Jet diameter in m.
k	Thermal conductivity of fluid (air). (W/mK)
Nu	Average Nusselt number.
Re	Reynolds number based on the diameter of the jet.

- X Non dimensional length along the jet.
- x Length along the jet, in m.
- ε Dimensionless relative roughness.

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Introduction

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1.1 General (Font size 12, Bold, Times New Roman, two blank spaces after article no, and Left Indent)

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Electronics cooling has served as a key enabling technology in the development of advanced microelectronic systems. With the increase in heat dissipation from microelectronics devices and the reduction in overall form factors, electronics cooling becomes a more and more important element of electronic product design.

Thermal management of electronic equipment has become an important issue because of increased power levels and the simultaneous miniaturization of the devices. With the advent of denser device packaging and faster intrinsic speeds, cost, reliability and size have been improved, but, unfortunately, thermal management have not followed at the same speed. As a result, it may be difficult to use the latest technology available.

1.2 Flow Phenomena (Font size 12, Bold, Times New Roman, two blank spaces after article no, and Left Indent)

The surface roughness encountered in practice varies in their shape, size, distribution and arrangement, micro-scopical surface property, characteristics behavior with flow etc. The roughness formed by sand particles or stone chips is called sand roughness. Nikurades described the sand roughness from technical point of view. The average absolute protrusion height of the roughness elements or the relative roughness heights with respect to some significant length are used to describe such roughness.

1.2.1 Types of Flow (Font size 12, Bold, Times New Roman, two blank spaces after article no, and Left Indent)

1. Axial Flow: Depending on the ratio of the height of the roughness ribs and pitch, such roughness can be divided into D-type and K-type roughness. When the error in the origin is proportional to the height of the roughness elements then the roughness is called K-type or sand grain roughness.

2. Radial Flow: For a D-type roughness the error in origin is a linear function of the distance in the downstream direction. For specific engineering purposes the roughness elements for different geometrical shape are sometimes used, their characteristic length defines these. Another type of roughness termed as tuft roughness are also sometimes encountered. The examples of these types of roughness are grassy lands, green bushes, cornfields, and green mosses grown in the ship hull.

Sl. No.	Velocity	Temperature	Altitude	Pressure
	m/Sec	°C	m	Kg/cm ²
1				
2				
3				
4				

Table 3.1: The value of different variables published by other investigator's are shown



Figure 4.1: Distribution co-efficient of pressure along axial locations varies with surface roughness at a particular flow situation.

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